

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A semiconductor processing module comprising:
 - a housing adapted to enclose a semiconductor wafer;
 - an ultraviolet radiation source disposed within the housing; and
 - a treatment medium disposed within the housing, wherein the treatment medium comprises ambient air.
2. (original) The module of claim 1, wherein the ultraviolet radiation source comprises an ultraviolet lamp.
- 3-5. (cancelled).
6. (original) The module of claim 1, further comprising a medium supply system disposed within the housing.
7. (original) The module of claim 6, wherein the medium supply system comprises a gas inlet.
8. (original) The module of claim 6, wherein the medium supply system comprises an ozone generator.

9. (currently amended) ~~The module of claim 1, further comprising~~ A semiconductor processing module comprising:

a housing adapted to enclose a semiconductor wafer;

an ultraviolet radiation source disposed within the housing;

a treatment medium disposed within the housing; and

_____ a medium conditioning system disposed within the housing, wherein the medium conditioning system is adapted to induce a partial vacuum within the housing.

10. (original) The module of claim 9, further comprising a medium supply system disposed within the medium conditioning system.

11. (cancelled).

12. (original) The module of claim 9, wherein the treatment medium is a vacuum induced by the medium conditioning system.

13. (original) The module of claim 9, wherein the medium conditioning system comprises a filtration system.

14-26 (canceled).

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27. (currently amended) A system for remediating organic contaminants from a copper seed layer deposited on an upper surface of a semiconductor wafer, the system comprising:

 a housing adapted to receive and enclose the semiconductor wafer;

 an ultraviolet radiation source disposed within the housing and adapted to expose the semiconductor wafer to ultraviolet radiation;

 an ozone generator adapted to supply ozone into the housing as a treatment medium for the semiconductor wafer; and

 a conditioning system disposed within the housing and adapted to filter contaminants from the ozone, wherein said conditioning system is further adapted to induce a partial vacuum within said housing.